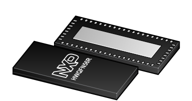

# SOT1033-2

**HWFLGA56, thermal enhanced very very thin fine-pitch land grid array package, 56 terminals, 0.5 mm pitch, 5 mm x 11 mm x 0.71 mm body**

**2 July 2021** **Package information**

## 1 Package summary

| | |
|---|---|
| **Terminal position code** | B (bottom) |
| **Package type descriptive code** | HWFLGA56 |
| **Package style descriptive code** | LGA (land grid array package) |
| **Mounting method type** | S (surface mount) |
| **Issue date** | 25-05-2018 |
| **Manufacturer package code** | 98ASA01239D |

**Table 1. Package summary**

| Parameter | Min | Nom | Max | Unit |
|---|---|---|---|---|
| package length | 10.9 | 11 | 11.1 | mm |
| package width | 4.9 | 5 | 5.1 | mm |
| package height | - | 0.71 | 0.77 | mm |
| nominal pitch | - | 0.5 | - | mm |
| actual quantity of termination | - | 56 | - | |

## 2 Package outline

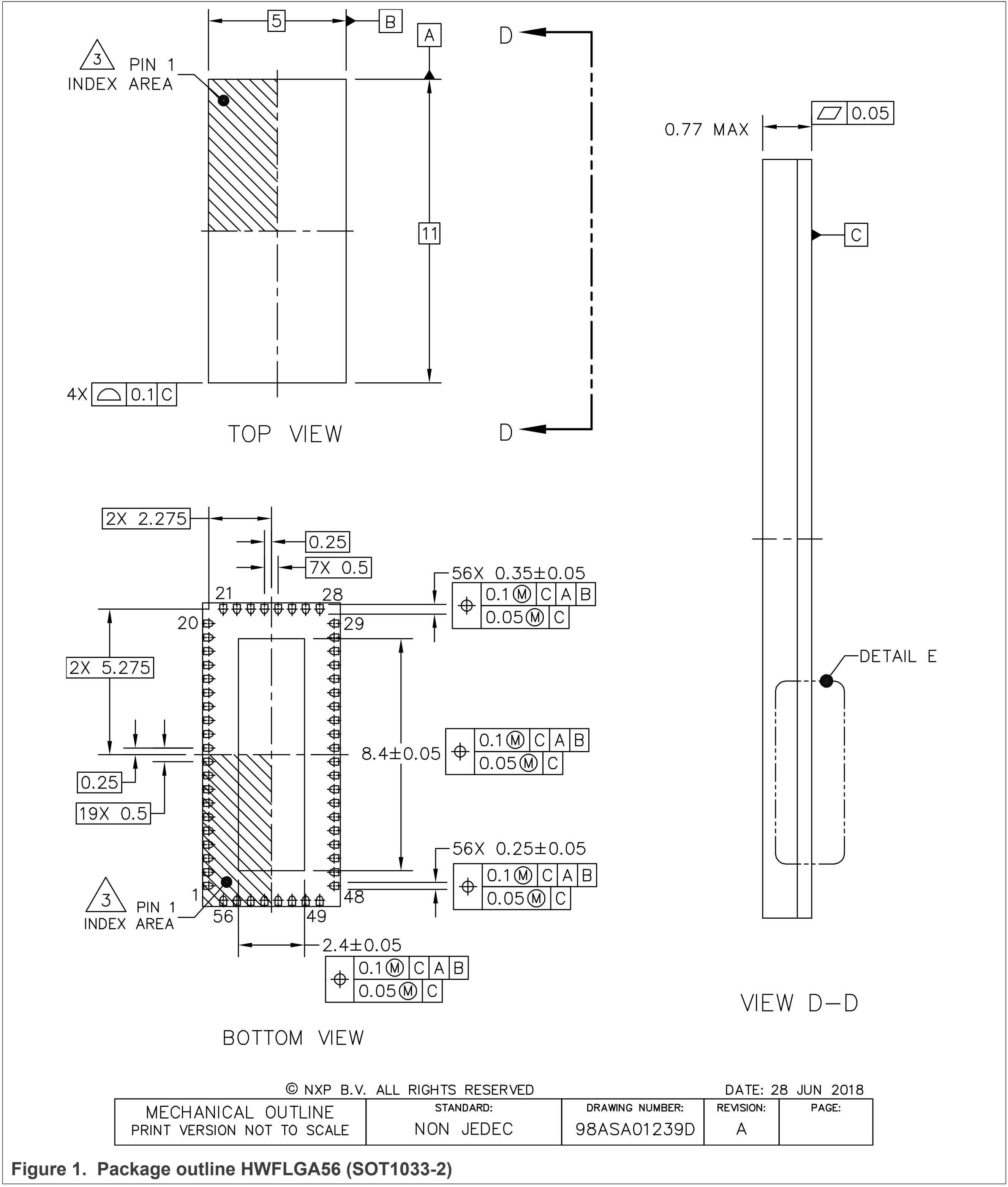


**Figure 1. Package outline HWFLGA56 (SOT1033-2)**



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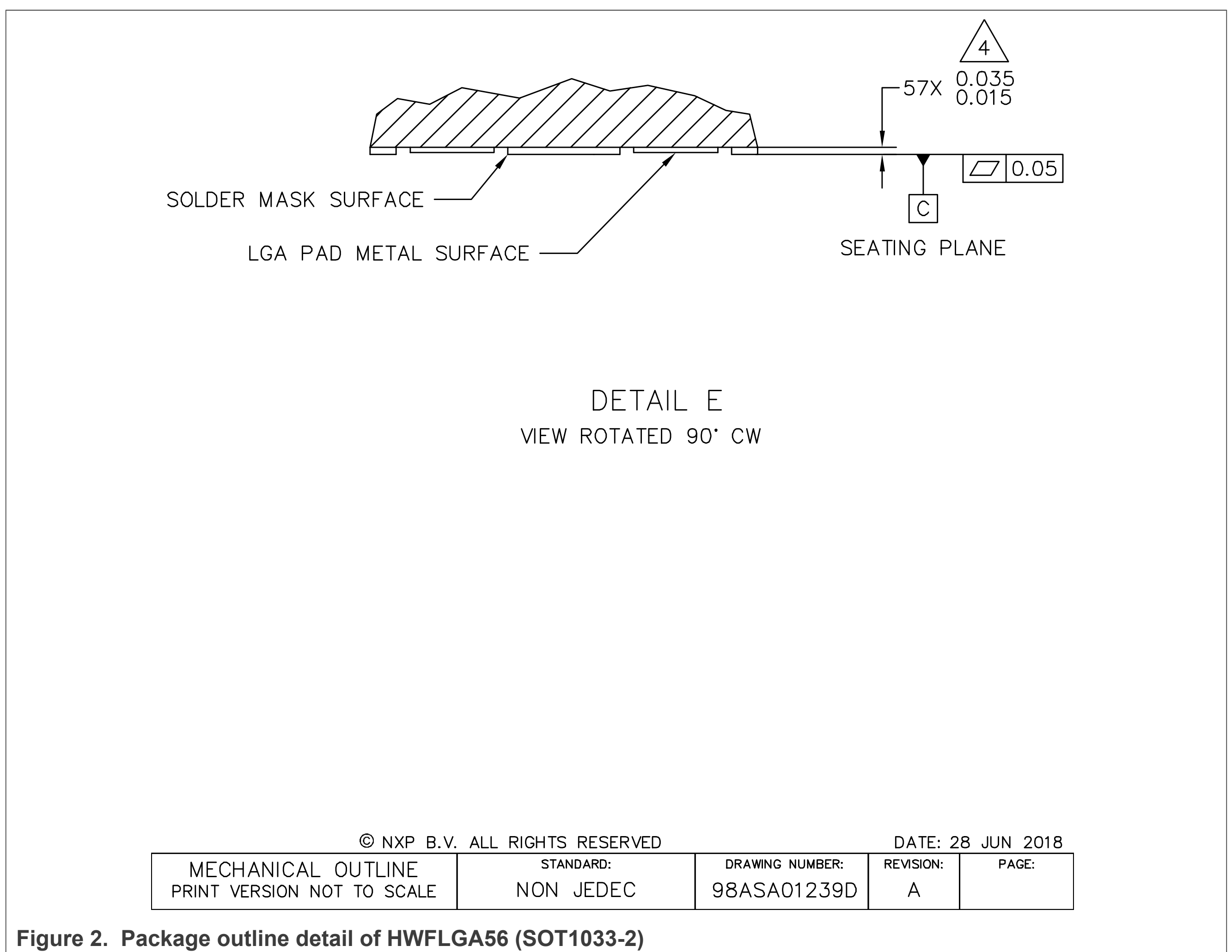


Figure 2. Package outline detail of HWFLGA56 (SOT1033-2)


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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4. COPLANARITY APPLIES TO LEADS AND EXPOSED PAD.

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DATE: 28 JUN 2018

| MECHANICAL OUTLINE<br>PRINT VERSION NOT TO SCALE | STANDARD:<br>NON JEDEC | DRAWING NUMBER:<br>98ASA01239D | REVISION:<br>A | PAGE: |
|---|---|---|---|---|

**Figure 3. Package outline note HWFLGA56 (SOT1033-2)**


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# 3 Soldering

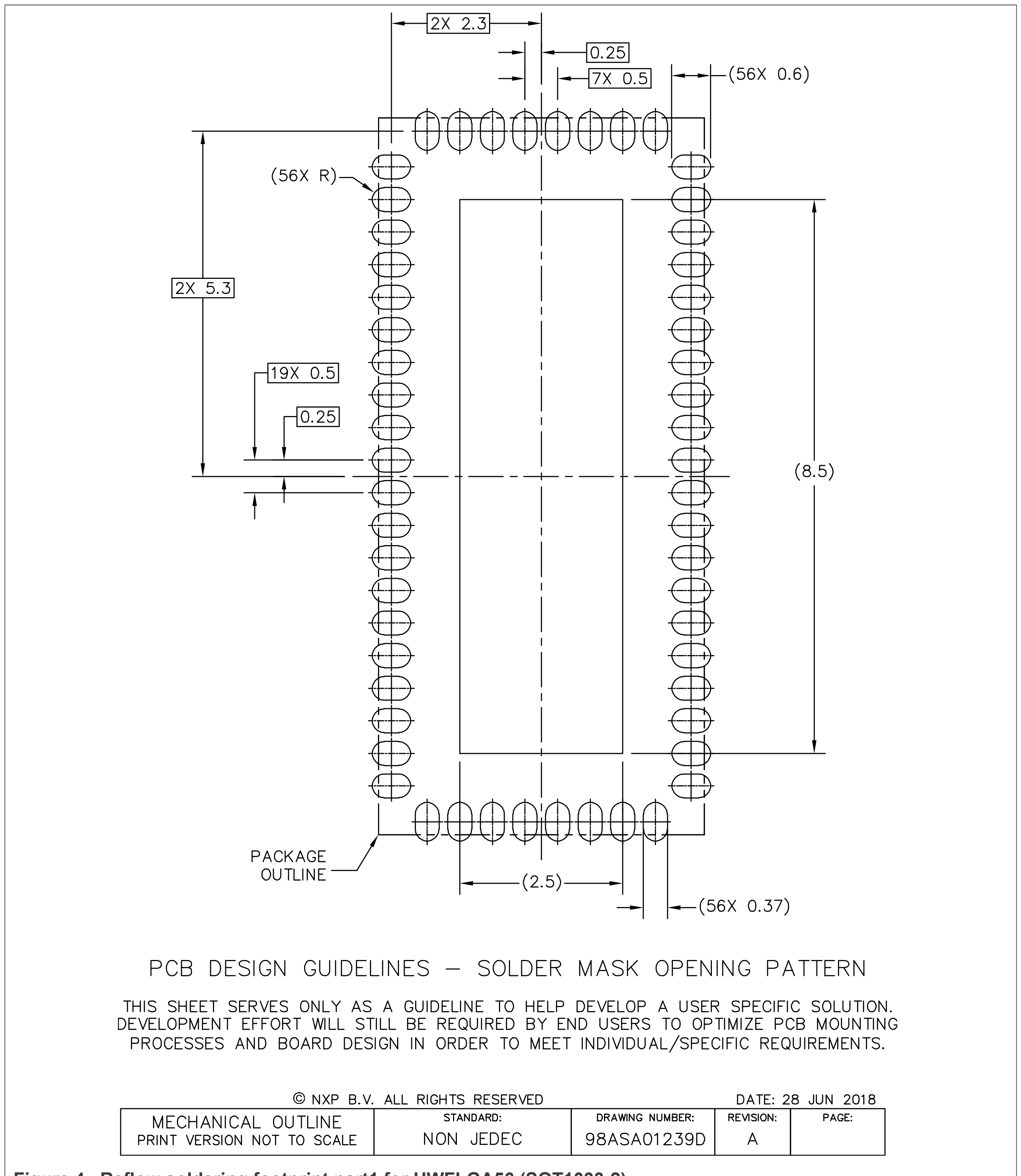


Figure 4. Reflow soldering footprint part1 for HWFLGA56 (SOT1033-2)


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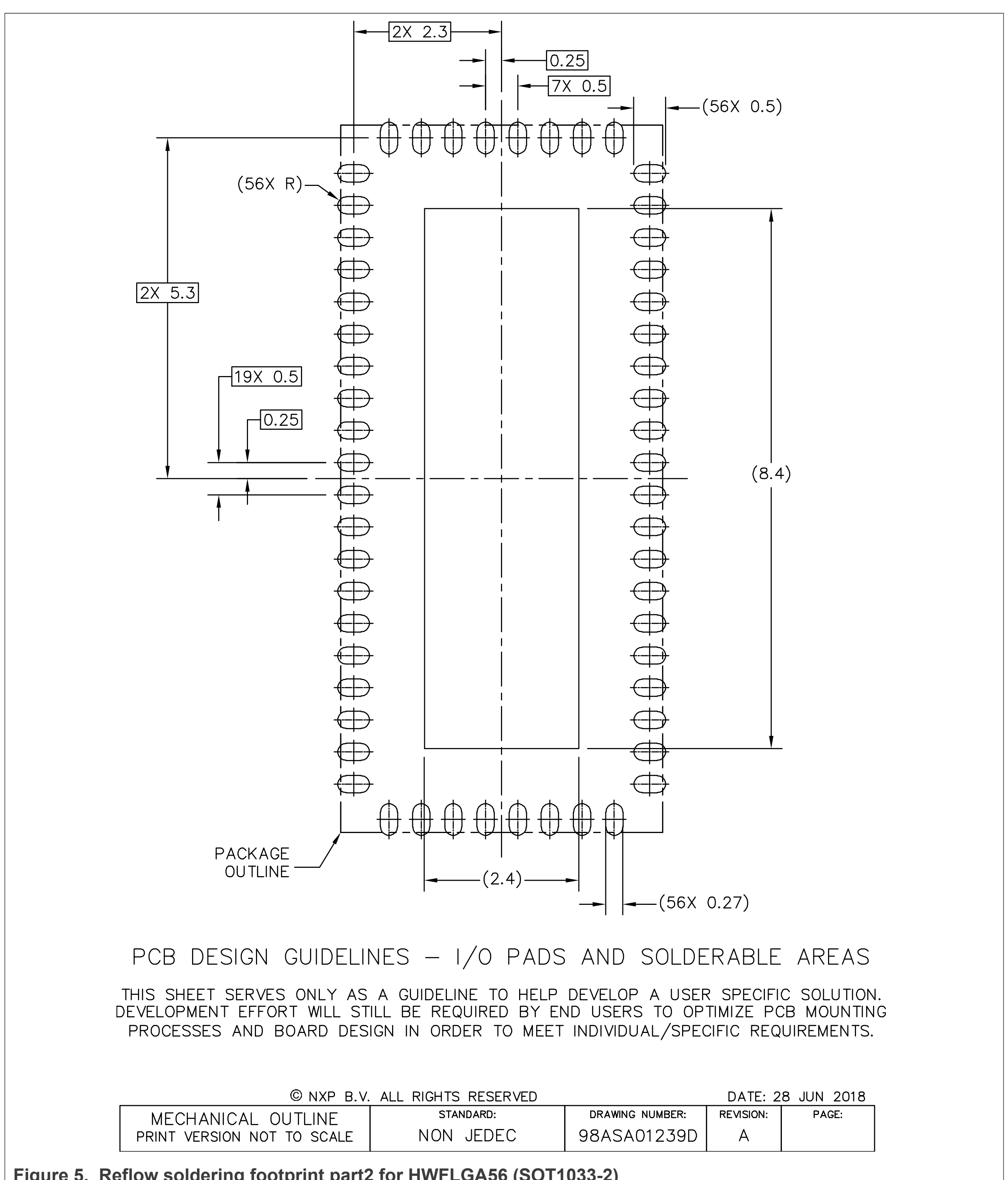


**Figure 5. Reflow soldering footprint part2 for HWFLGA56 (SOT1033-2)**



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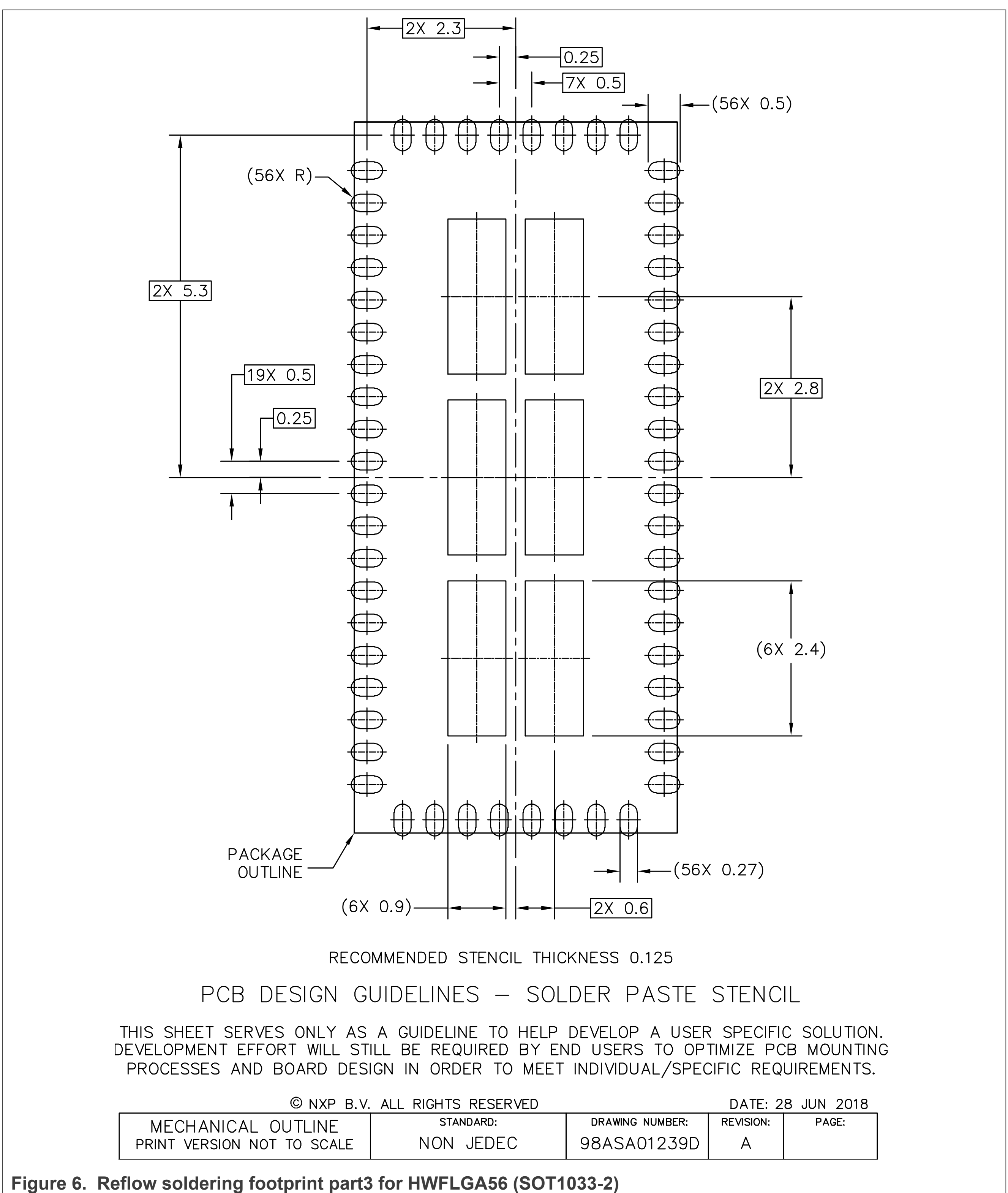


Figure 6. Reflow soldering footprint part3 for HWFLGA56 (SOT1033-2)



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# 4 Legal information

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